



HVD191

Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

REJ03G0015-0100Z

Rev.1.00

Apr.28.2003

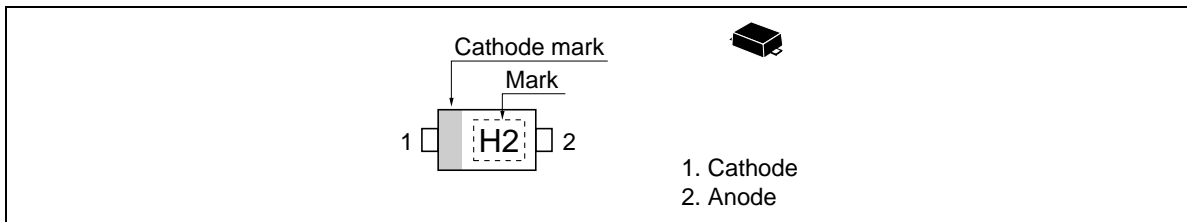
Features

- Low capacitance. ($C \leq 0.37$ pF)
- Low forward resistance. ($r_f \leq 2.5 \Omega$)
- Super small Flat Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVD191	H2	SFP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V _R	30	V
Forward current	I _F	100	mA
Power dissipation	Pd	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

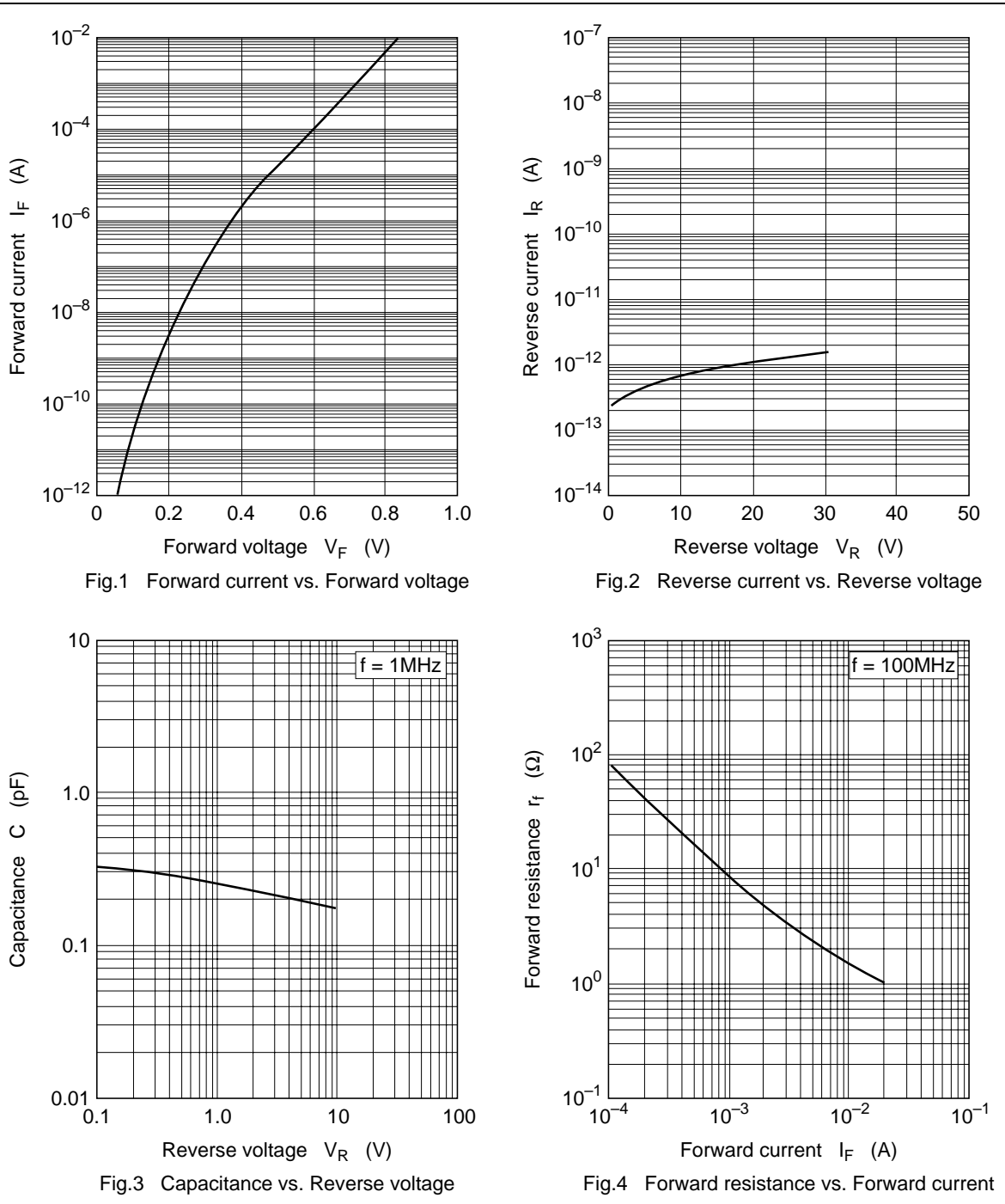
Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V _F	—	—	1.0	V	I _F = 10 mA
Reverse current	I _R	—	—	0.1	μA	V _R = 30 V
Capacitance	C	—	—	0.37	pF	V _R = 1 V, f = 1 MHz
Forward resistance	r _f	—	—	2.5	Ω	I _F = 10 mA, f = 100 MHz

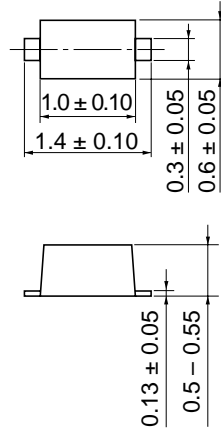
- Notes: 1. Please do not use the soldering iron due to avoid high stress to the SFP package.
2. The material of lead is exposed for cutting plane. Therefore, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic



Package Dimensions

As of January, 2003
Unit: mm



Package Code	SFP
JEDEC	—
JEITA	—
Mass (reference value)	0.0010 g

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Keep safety first in your circuit designs!

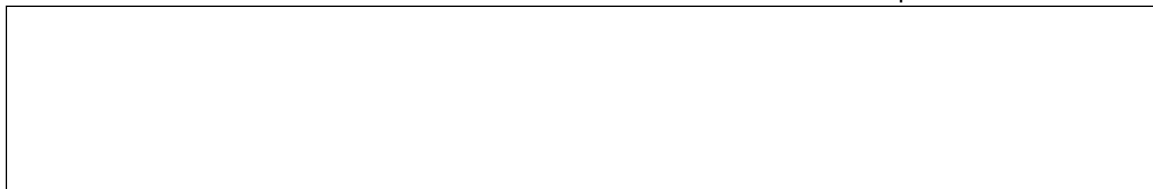
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